XICOR®

64K	**X24645**	8192 x 8 Bit

Advanced 2-Wire Serial EEPROM with Block Lock™ Protection

FEATURES

- **2.7V to 5.5V power supply**
- **Low power CMOS**
  - **—Active read current less than 1mA**
  - **—Active write current less than 3mA**
  - **—Standby current less than 1µA**
- **Internally organized 8192 x 8**
- **New programmable block lock protection**
  - **—Software write protection**
  - **—Programmable hardware write protect**
- **Block lock (0, 1/4, 1/2, or all of the EEPROM array)**
- **2-wire serial interface**
- **Bidirectional data transfer protocol**
- **32-byte page write mode**
  - **—Minimizes total write time per byte**
- **Self timed write cycle**
  - **—Typical write cycle time of 5ms**
- **High reliability**
  - **—Endurance: 1,000,000 cycles**
  - **—Data retention: 100 years**
- **Available packages**
  - **—8-lead SOIC (JEDEC)**

DESCRIPTION

The X24645 is a CMOS 65,536-bit serial EEPROM, internally organized 8192 x 8. The X24645 features a serial interface and software protocol allowing operation on a simple two wire bus.

Two device select inputs (S_1, S_2) allow up to four devices to share a common two wire bus.

A Write Protect Register at the highest address location, 1FFFh, provides three new write protection features: Software Write Protect, Block Write Protect, and Hardware Write Protect. The software write protect feature prevents any nonvolatile writes to the X24645 until the WEL bit in the write protect register is set. The block write protect feature allows the user to individually write protect four blocks of the array by programming two bits in the write protect register. The programmable hardware write protect feature allows the user to install the X24645 with WP tied to V_{CC}, program the entire memory array in place, and then enable the hardware write protection by programming a WPEN bit in the write protect register. After this, selected blocks of the array, including the write protect register itself, are permanently write protected, as long as WP remains HIGH.

Xicor EEPROMs are designed and tested for applications requiring extended endurance. Inherent data retention is greater than 100 years.

BLOCK DIAGRAM
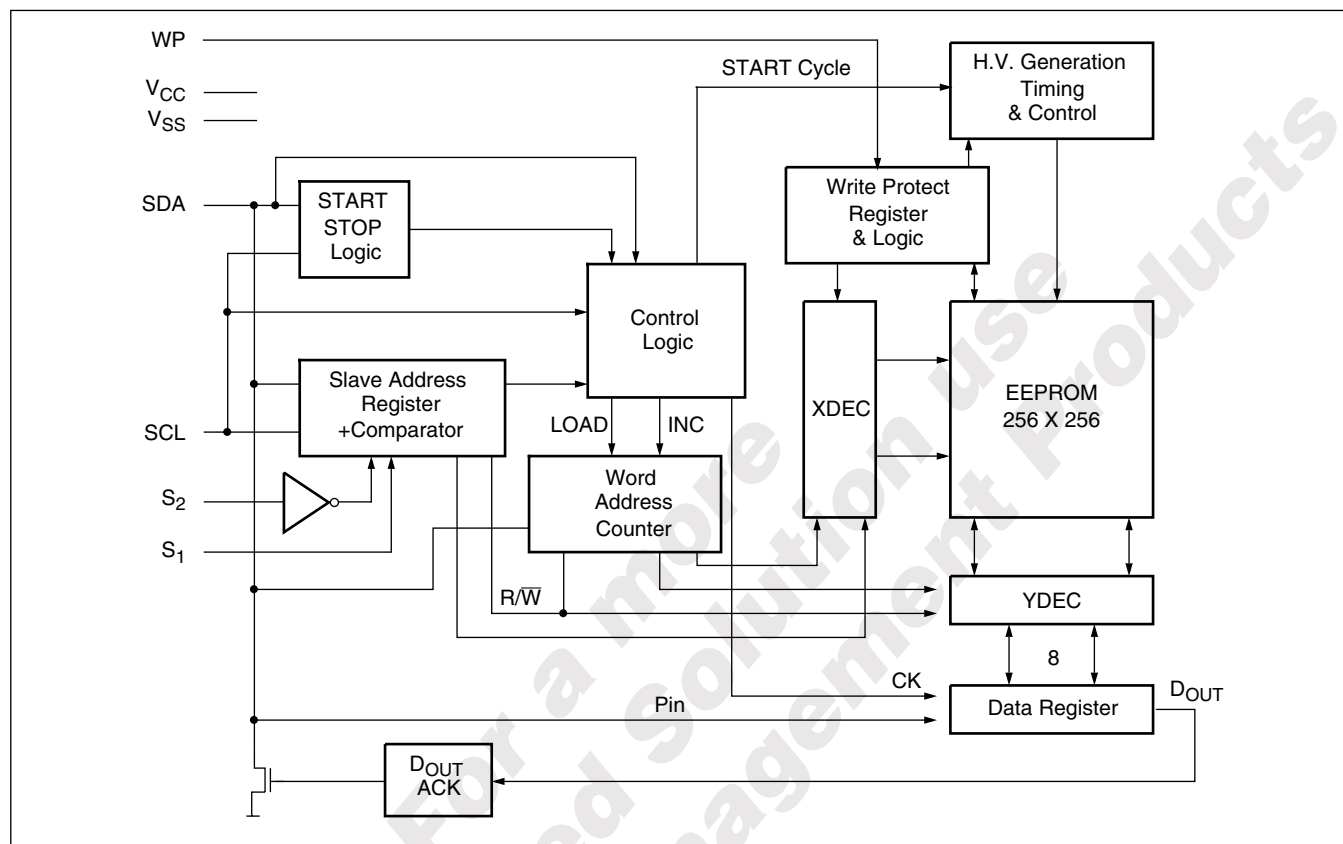
PIN DESCRIPTIONS

Serial Clock (SCL)

The SCL input is used to clock all data into and out of the device.

Serial Data (SDA)

SDA is a bidirectional pin used to transfer data into and out of the device. It is an open drain output and may be wire-ORed with any number of open drain or open collector outputs.

An open drain output requires the use of a pull-up resistor. For selecting typical values, refer to the Pull-up resistor selection graph at the end of this data sheet.

Device Select (S$_1$, S$_2$)

The device select inputs (S$_1$, S$_2$) are used to set the first and second bits of the 8-bit slave address. This allows up to four X24645 devices to share a common bus. These inputs can be static or actively driven. If used statically, they must be tied to V$_{SS}$ or V$_{CC}$ as appropriate. If actively driven, they must be driven with CMOS levels (driven to V$_{CC}$ or V$_{SS}$).

Write Protect (WP)

The write protect input controls the hardware write protect feature. When held LOW, hardware write protection is disabled, and the X24645 can be written normally. When this input is held HIGH, and the WPEN bit in the write protect register is set HIGH, write protection is enabled, and nonvolatile writes are disabled to the selected blocks, as well as the write protect register itself.

X24645 – Preliminary Information

PIN NAMES

Symbol	Description
S_1, S_2	Device Select Inputs
SDA	Serial Data
SCL	Serial Clock
WP	Write Protect
V_{SS}	Ground
V_{CC}	Supply Voltage
NC	No Connect

PIN CONFIGURATIONS

8-Lead SOIC

```
NC   ▭ 1        8 ▭ VCC
S1   ▭ 2  X24645 7 ▭ WP
S2   ▭ 3        6 ▭ SCL
VSS  ▭ 4        5 ▭ SDA
```
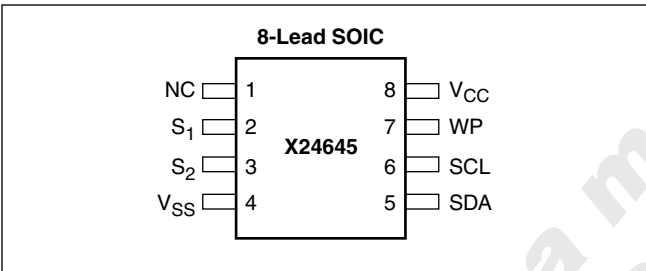
DEVICE OPERATION

The X24645 supports a bidirectional bus oriented protocol. The protocol defines any device that sends data onto the bus as a transmitter, and the receiving device as the receiver. The device controlling the transfer is a master and the device being controlled is the slave. The master will always initiate data transfers, and provide the clock for both transmit and receive operations. Therefore, the X24645 will be considered a slave in all applications.

Clock and Data Conventions

Data states on the SDA line can change only during SCL LOW. SDA state changes during SCL HIGH are reserved for indicating start and stop conditions. Refer to Figures 1 and 2.

Start Condition

All commands are preceded by the start condition, which is a HIGH to LOW transition of SDA when SCL is HIGH. The X24645 continuously monitors the SDA and SCL lines for the start condition and will not respond to any command until this condition has been met.

Stop Condition

All communications must be terminated by a stop condition, which is a LOW to HIGH transition of SDA when SCL is HIGH. The stop condition is also used to place the device into the standby power mode after a read sequence. A stop condition can only be issued after the transmitting device has released the bus.
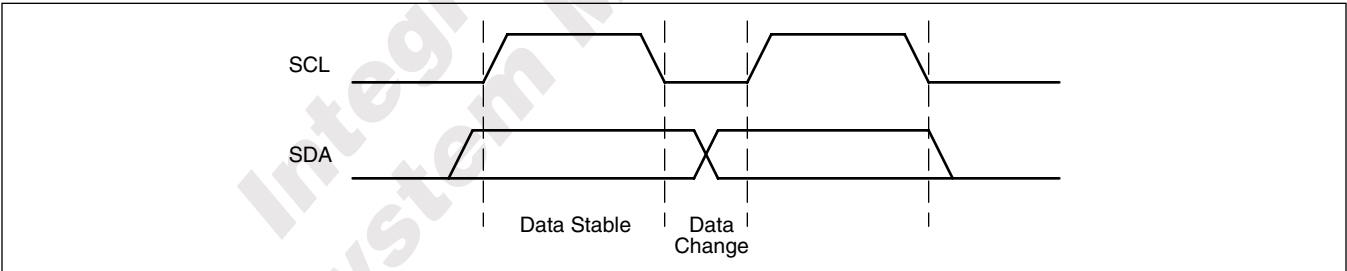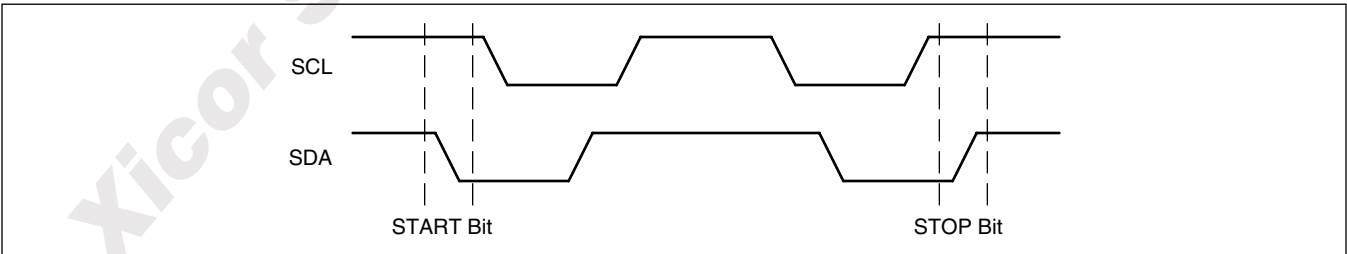
Figure 1. Data Validity

Data Stable   Data Change

Figure 2. Definition of Start and Stop


START Bit   STOP Bit

Acknowledge

Acknowledge is a software convention used to indicate successful data transfer. The transmitting device, either master or slave, will release the bus after transmitting eight bits. During the ninth clock cycle the receiver will pull the SDA line LOW to acknowledge that it received the eight bits of data. Refer to Figure 3.

The X24645 will respond with an acknowledge after recognition of a start condition and its slave address. If both the device and a write operation have been selected, the X24645 will respond with an acknowledge after the receipt of each subsequent 8-bit word.

In the read mode the X24645 will transmit eight bits of data, release the SDA line and monitor the line for an acknowledge. If an acknowledge is detected and no stop condition is generated by the master, the X24645 will continue to transmit data. If an acknowledge is not detected, the X24645 will terminate further data transmissions. The master must then issue a stop condition to return the X24645 to the standby power mode and place the device into a known state.

Figure 3. Acknowledge Response From Receiver
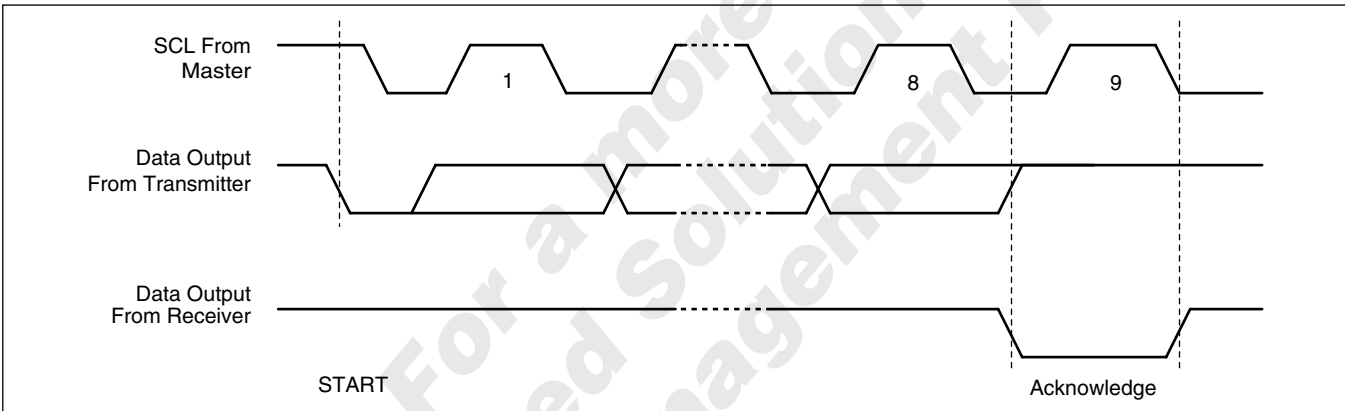
DEVICE ADDRESSING

Following a start condition, the master must output the address of the slave it is accessing (see Figure 4). The next two bits are the device select bits. A system could have up to four X24645s on the bus. The four addresses are defined by the state of the S_1 and S_2 inputs. S_2 of the slave address must be the inverse of the S_2 input pin.

Figure 4. Slave Addressing
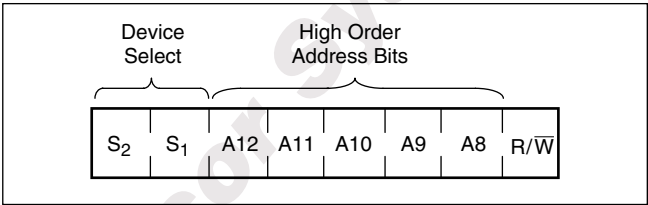
The next five bits of the slave address are an extension of the array's address, and are concatenated with the eight bits of address in the byte address field, providing direct access to the whole 8192 x 8 array.

The last bit of the slave address defines the operation to be performed. When set HIGH a read operation is selected, when set LOW, a write operation is selected.

Following the start condition, the X24645 monitors the SDA bus, comparing the slave address being transmitted with its slave address device type identifier. Upon a correct compare, the X24645 outputs an acknowledge on the SDA line. Depending on the state of the $R/\overline{W}$ bit, the X24645 will execute a read or write operation.
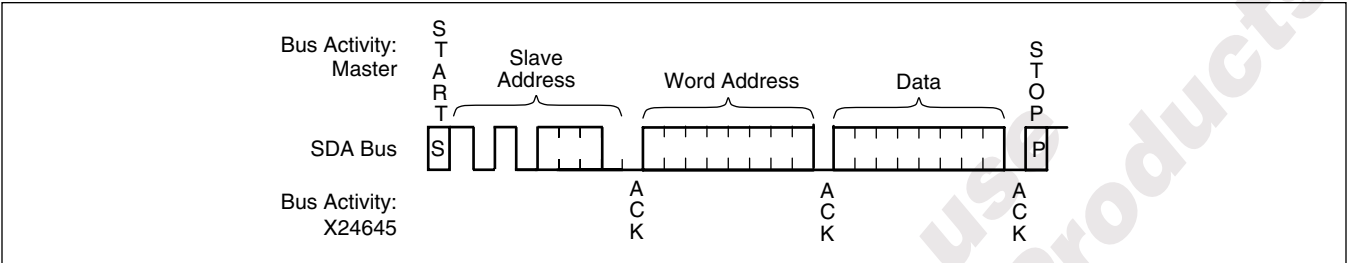
WRITE OPERATIONS

Byte Write

For a write operation, the X24645 requires a second address field. This address field is the byte address, comprised of eight bits, providing access to any one of 8192 words in the array. Upon receipt of the byte address, the X24645 responds with an acknowledge and awaits the next eight bits of data, again responding with an acknowledge. The master then terminates the transfer by generating a stop condition, at which time

the X24645 begins the internal write cycle to the non-volatile memory. While the internal write cycle is in progress the X24645 inputs are disabled, and the device will not respond to any requests from the master. Refer to Figure 5 for the address, acknowledge and data transfer sequence.

**Figure 5. Byte Write**

Page Write

The X24645 is capable of a 32-byte page write operation. It is initiated in the same manner as the byte write operation, but instead of terminating the write cycle after the first data word is transferred, the master can transmit up to thirty-one more bytes. After the receipt of each byte, the X24645 will respond with an acknowledge.

After the receipt of each byte, the five low order address bits are internally incremented by one. The high order eight bits of the address remain constant. If the master should transmit more than 32 bytes prior to generating the stop condition, the address counter will "roll over" and the previously written data will be over-written. As with the byte write operation, all inputs are disabled until completion of the internal write cycle. Refer to Figure 6 for the address, acknowledge, and data transfer sequence.

Figure 6. Page Write
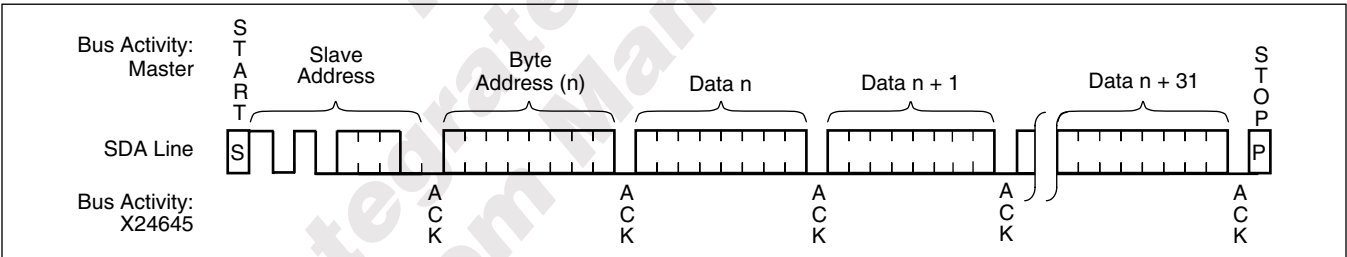
Acknowledge Polling

The max write cycle time can be significantly reduced using acknowledge polling. To initiate acknowledge polling, the master issues a start condition followed by the slave address byte for a write or read operation. If the device is still busy with the high voltage cycle, then no ACK will be returned. If the device has completed the write operation, an ACK will be returned and the host can then proceed with the read or write operation. Refer to Flow 1.

Flow 1. ACK Polling Sequence
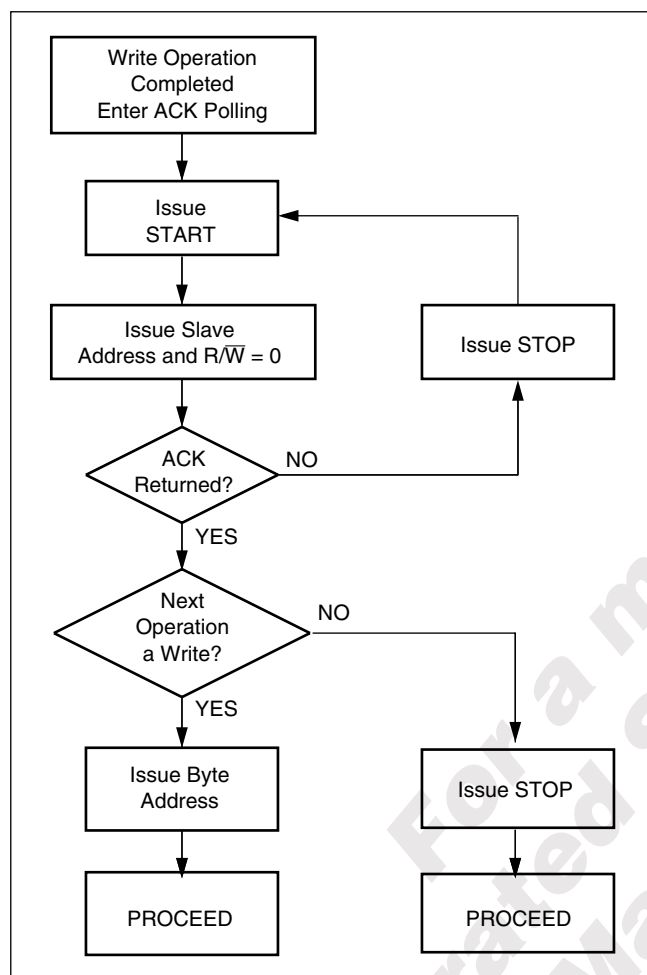
READ OPERATIONS

Read operations are initiated in the same manner as write operations with the exception that the R/W bit of the slave address is set HIGH. There are three basic read operations: current address read, random read and sequential read.

It should be noted that the ninth clock cycle of the read operation is not a "don't care." To terminate a read operation, the master must either issue a stop condition during the ninth cycle or hold SDA HIGH during the ninth clock cycle and then issue a stop condition.

Current Address Read

Internally the X24645 contains an address counter that maintains the address of the last byte read, incremented by one or the exact address of the last byte written. Therefore, if the last access read was to address n, the next read operation would access data from address n + 1. Upon receipt of the slave address with the R/W set HIGH, the X24645 issues an acknowledge and transmits the byte. The read operation is terminated by the master by not responding with an acknowledge and then issuing a stop condition. Refer to Figure 7 for the sequence of address, acknowledge and data transfer.

Figure 7. Current Address Read
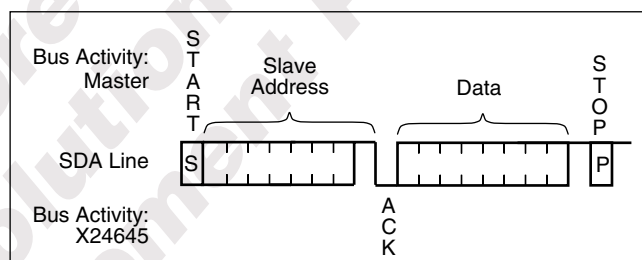
Random Read

Random read operations allow the master to access any memory location in a random manner. Prior to issuing the slave address with the R/W bit set HIGH, the master must first perform a "dummy" write operation. The master issues the start condition, and the slave address with the R/W bit set LOW, followed by the byte address it is to read. After the word address acknowledge, the master immediately reissues the start condition and the slave address with the R/W bit set HIGH. This will be followed by an acknowledge from the X24645 and then by the data byte. The read operation is terminated by the master by not responding with an acknowledge and then issuing a stop condition. Refer to Figure 8 for the address, acknowledge and data transfer sequence.
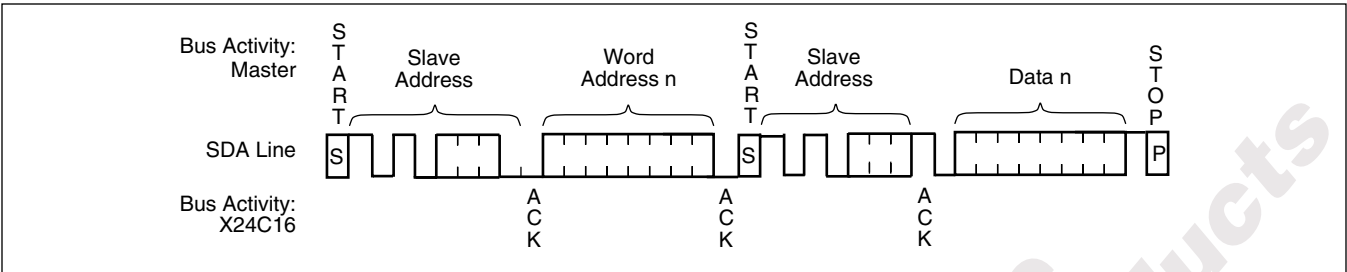
Figure 8. Random Read

Sequential Read

Sequential reads can be initiated as either a current address read or random access read. The first byte is transmitted as with the other modes; however, the master now responds with an acknowledge, indicating it requires additional data. The X24645 continues to output data for each acknowledge received. The read operation is terminated by the master by not responding with an acknowledge, and then issuing a stop condition.

The data output is sequential, with the data from address n followed by the data from n + 1. The address counter for read operations increments all address bits, allowing the entire memory contents to be serially read during one operation. At the end of the address space (address 8191), the counter "rolls over" to 0 and the X24645 continues to output data for each acknowledge received. Refer to Figure 9 for the address, acknowledge and data transfer sequence.
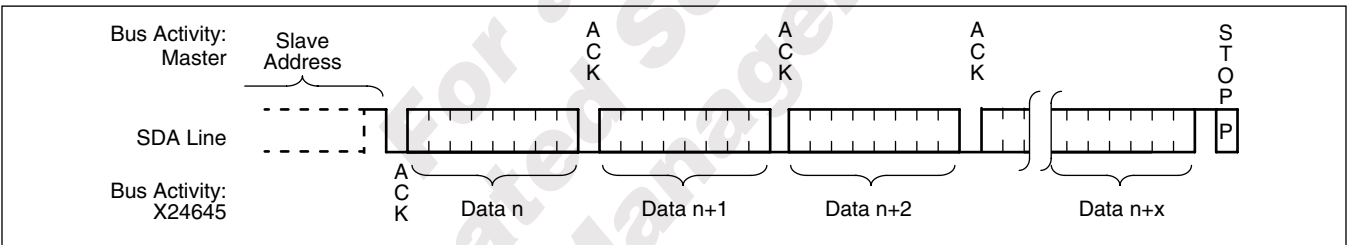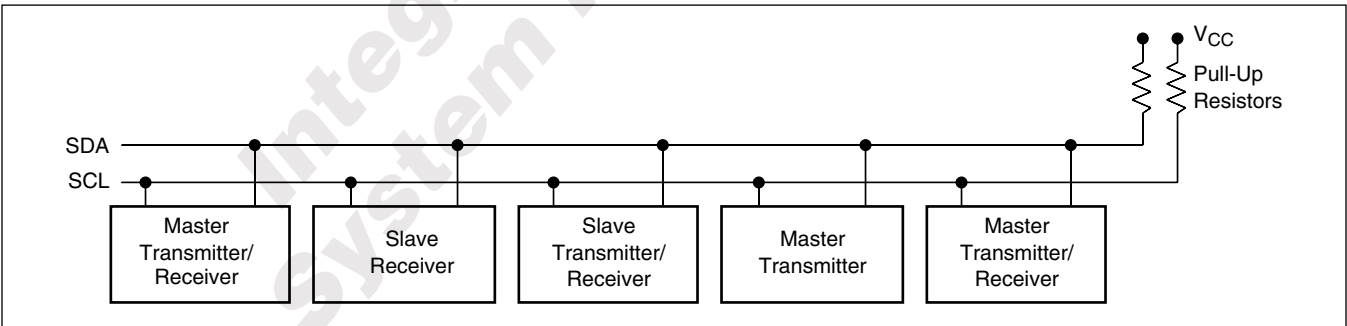
Figure 9. Sequenctial Read

Figure 10. Typical System Configuration

WRITE PROTECT REGISTER

The write protect register (WPR) is located at the highest address, 1FFFh.

Write Protect Register

WPR (ADDR = FFFh)

7	6	5	4	3	2	1	0
WPEN	0	0	BP1	BP0	RWEL	WEL	0

WPR.1 = WEL
– "Write Enable" Latch (Volatile)
  0 = Write enable latch reset, writes disabled
  1 = Write enable latch set, writes enabled

If WEL = "0" then "no ACK" after first byte of input data.

WPR.2 = RWEL
– "Register Write Enable" Latch (Volatile)
  0 = Register write enable latch reset, writes disabled
  1 = Register write enable latch set, writes enabled

WPR.3, WPR.4 = BP0, BP1
– Block Protect Bits (Nonvolatile)
  (See Block Protect section for definition)

WPR.7 = WPEN
– Write Protect Enable Bit (Nonvolatile)
  (See Hardware Write Protect section for definition)

Writing to the Write Protect Register

The write protect register is written by performing a random write of one byte directly to address, 1FFFh. If a page write is performed starting with any address other than 1FFF, the byte in the array at address 1FFFh will be written instead of the write protect register (assuming writes are not disabled by the block protect register).

The state of the write protect register can be read by performing a random read at address 1FFFh at any time. If a sequential read starting at any other address than 1FFFh is performed, the contents of the byte in the array at 1FFFh is read out instead of the write protect register.

WEL and RWEL are volatile latches that power-up in the LOW (disabled) state. A write to any address other than 1FFFh, where the Write Protect Register is located, will be ignored (no ACK) until the WEL bit is set HIGH. The WEL bit is set by writing 0000001x to address 1FFFh. Once set, WEL remains HIGH until either reset (by writing 00000000 to 1FFFh) or until the part powers-up again. The RWEL bit controls writes to

the block protect bits. RWEL is set by first setting WEL to "1" and then writing 0000011x to address 1FFFh. RWEL must be set in order to change the block protect bits, BP0 and BP1, or the WPEN bit. RWEL is reset when the block protect or WPEN bits are changed, or when the part powers-up again.

Programming the BP or WPEN Bits

A three step sequence is required to change the non-volatile block protect or write protect enable:

1) Set WEL = 1 (write 00000010 to address 1FFFh, volatile write cycle)

(Start)

2) Set RWEL = 1 (write 00000110 to address 1FFFh, volatile write cycle)

(Start)

3) Set BP1, BP0, and/or WPEN bits (Write w00yz010 to address 1FFFh)

w = WPEN, y = BP1, Z = BP0,

(Stop)

Step 3 is a nonvolatile write cycle, requiring 10ms to complete. RWEL is reset to "0" by this write cycle, requiring another write cycle to set RWEL again before the block protect bits can be changed. RWEL must be "0" in step 3; if w00yz110 is written to address 1FFFh, RWEL is set but WPEN, BP1 and BP0 are not changed (the device remains at step 2).

Block Protect Bits

The Block Protect Bits BP0 and BP1 determine which blocks of the memory are write-protected:

Programmable Hardware Write Protect

The Write Protect (WP) pin and the Write Protect ENable (WPEN) bit in the Write Protect Register control the programmable hardware write protect feature. Hardware write protection is enabled when the WP pin and the WPEN bit are both high, and disabled when either the WP pin is low or the WPEN bit is low. When the chip is hardware write-protected, nonvolatile writes are disabled to the Write Protect Register, including the BP bits and the WPEN bit itself, as well as to block protected sections in the memory array. Only the sections of the memory array that are not block-protected can be written. Note that since the WPEN bit is write-protected, it cannot be changed back to a low state,

and write protection is disabled as long as the the WP pin is held high. Table 2 defines the write protection status for each state of WPEN and WP.

Block Protect Bits

The block protect bits BP0 and BP1 determine which blocks of the memory are write-protected:

Table 1. Block Protect Bits

BP1	BP0	Protected Addresses	
0	0	None	
0	1	1800h–1FFFh	Upper 1/4
1	0	1000h–1FFFh	Upper 1/2
1	1	0000h–1FFFh	Full Array (WPR not included)

Programmable Hardware Write Protect

The Write Protect (WP) pin and the Write Protect Enable (WPEN) bit in the write protect register control the programmable hardware write protect feature. Hardware write protection is enabled when the WP pin is HIGH and the WPEN bit is "1", and disabled when either the WP pin is LOW or the WPEN bit is "0". When the chip is hardware write-protected, nonvolatile writes are disabled to the write protect register, including the BP bits and the WPEN bit itself, as well as to block-protected sections in the memory array. Only the sections of the memory array that are not block-protected can be written. Note that since the WPEN bit is write-protected, it cannot be changed back to a LOW state, and write protection is disabled as long as the the WP pin is held HIGH. Table 2 defines the write protection status for each state of WPEN and WP.

Table 2. Write Protect Status Table

WP	WPEN	Memory Array (Not Block Protected)	Memory Array (Block Protected)	BP Bits	WPEN Bit
L	X	Writable	Protected	Writable	Writable
X	0	Writable	Protected	Writable	Writable
H	1	Writable	Protected	Protected	Protected

X24645 – Preliminary Information

ABSOLUTE MAXIMUM RATINGS

Temperature under bias X24645 ....–65 to +135°C
Storage temperature ....–65 to +150°C
Voltage on any pin with respect to V_{SS} ....–1V to +7V
D.C. output current 5mA
Lead temperature (soldering, 10 seconds).........300°C

COMMENT

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only; functional operation of the device (at these or any other conditions above those indicated in the operational sections of this specification) is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS

Temperature	Min.	Max.
Commercial	0°C	+70°C
Industrial	–40°C	+85°C

Supply Voltage	Limits
X24645-2.7	2.7V to 5.5V

D.C. OPERATING CHARACTERISTICS

Symbol	Parameter	Limits		Unit	Test Conditions
		Min.	Max.		
I_{CC1}	V_{CC} supply current (Read)		1	mA	SCL = V_{CC} X 0.1/V_{CC} X 0.9 Levels @ 100kHz, SDA = Open, All Other Inputs = V_{SS} or V_{CC} – 0.3V
I_{CC2}	V_{CC} supply current (Write)		3	mA	
I_{SB1}[1]	V_{CC} standby current		50	µA	SCL = SDA = V_{CC}, All Other Inputs = V_{SS} or V_{CC} – 0.3V, V_{CC} = 5V ± 10%
I_{SB2}[1]	V_{CC} standby current		1	µA	SCL = SDA = V_{CC}, All Other Inputs = V_{SS} or V_{CC} – 0.3V, V_{CC} = 2.7V
I_{LI}	Input leakage current		10	µA	V_{IN} = V_{SS} to V_{CC}
I_{LO}	Output leakage current		10	µA	V_{OUT} = V_{SS} to V_{CC}
V_{IL}[2]	Input LOW voltage	–1	V_{CC} x 0.3	V	
V_{IH}[2]	Input HIGH voltage	V_{CC} x 0.7	V_{CC} + 0.5	V	
V_{OL}	Output LOW voltage		0.4	V	I_{OL} = 3mA, V_{CC} = 4.5V

CAPACITANCE T_A = +25°C, f = 1MHz, V_{CC} = 5V

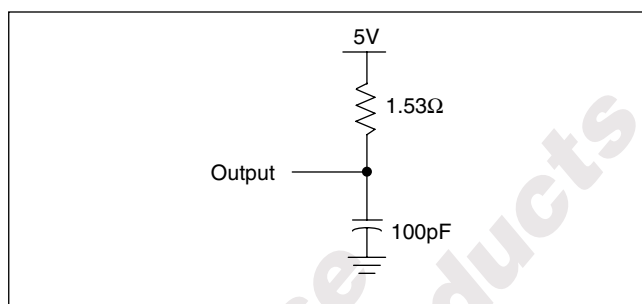| Symbol	Parameter	Max.	Unit	Test Conditions
$C_{I/O}$[3]	Input/Output capacitance (SDA)	8	pF	$V_{I/O}$ = 0V
C_{IN}[3]	Input capacitance (S_1, S_2, SCL)	6	pF	V_{IN} = 0V

Notes: (1) Must perform a stop command prior to measurement.

(2) V_{IL} min. and V_{IH} max. are for reference only and are not 100% tested.

(3) This parameter is periodically sampled and not 100% tested.

A.C. CONDITIONS OF TEST

Input pulse levels	V_{CC} x 0.1 to V_{CC} x 0.9
Input rise and fall times	10ns
Input and output timing levels	V_{CC} X 0.5

EQUIVALENT A.C. LOAD CIRCUIT

A.C. OPERATING CHARACTERISTICS (Over the recommended operating conditions, unless otherwise specified.)

Read & Write Cycle Limits

Symbol	Parameter	Min.	Max.	Unit
f_{SCL}	SCL clock frequency	0	400	kHz
T_I	Noise suppression time constant at SCL, SDA inputs		100	ns
t_{AA}	SCL LOW to SDA data out valid	0.3	3.5	µs
t_{BUF}	Time the bus must be free before a new transmission can start	4.7		µs
$t_{HD:STA}$	Start condition hold time	4		µs
t_{LOW}	Clock LOW period	4.7		µs
t_{HIGH}	Clock HIGH period	4		µs
$t_{SU:STA}$	Start condition setup time (for a repeated start condition)	4.7		µs
$t_{HD:DAT}$	Data in hold time	0		µs
$t_{SU:DAT}$	Data in setup time	250		ns
t_R	SDA and SCL rise time		1	µs
t_F	SDA and SCL fall time		300	ns
$t_{SU:STO}$	Stop Condition setup time	4.7		µs
t_{DH}	Data out hold time	300		ns

POWER-UP TIMING[4]

Symbol	Parameter	Max.	Unit
t_{PUR}	Power-up to read operation	1	ms
t_{PUW}	Power-up to write operation	5	ms

Note: (4) t_{PUR} and t_{PUW} are the delays required from the time V_{CC} is stable until the specified operation can be initiated. These parameters are periodically sampled and not 100% tested.
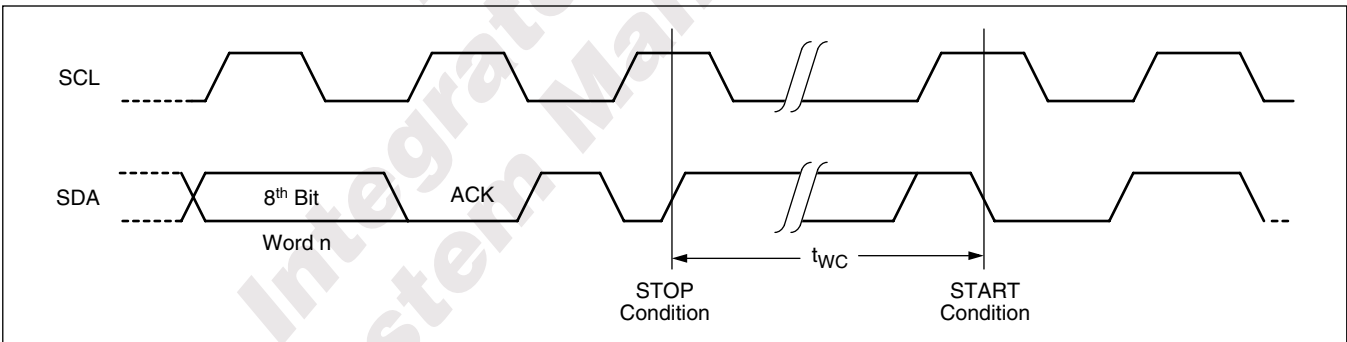
Bus Timing
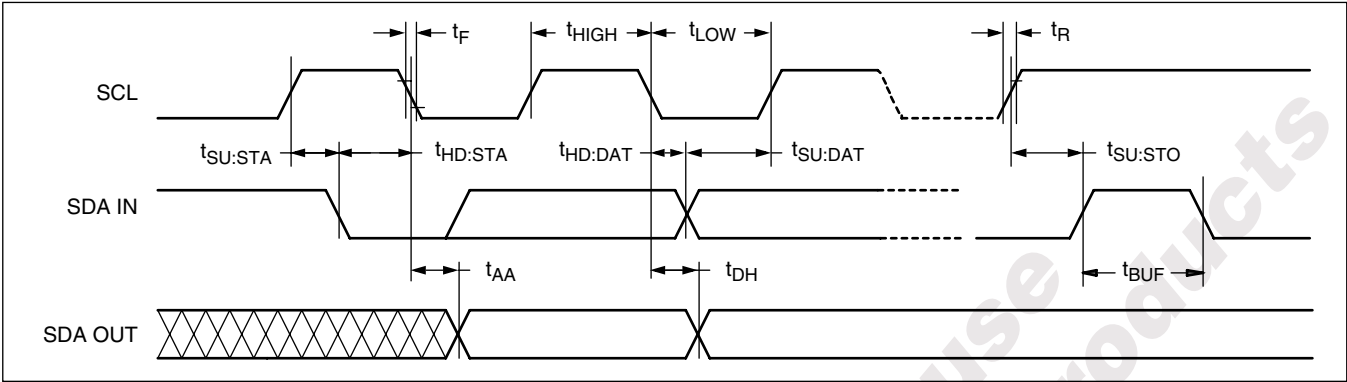
Write Cycle Limits

Symbol	Parameter	Min.	Typ.[5]	Max.	Unit
t_{WC}[6]	Write Cycle Time		5	10	ms

Notes: (5) Typical values are for $T_A = 25°C$ and nominal supply voltage (5V).

(6) t_{WR} is the minimum cycle time to be allowed from the system perspective unless polling techniques are used. It is the maximum time the device requires to automatically complete the internal write operation.
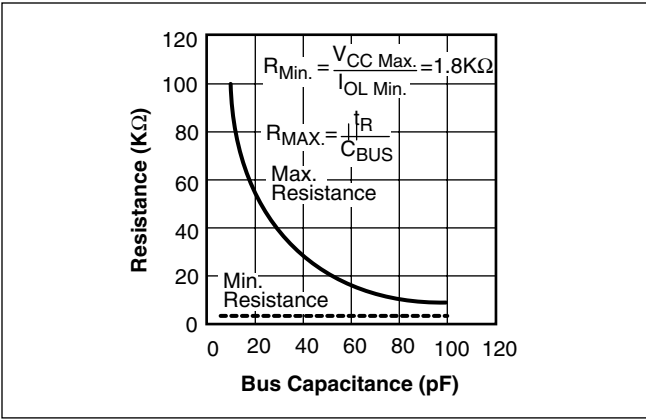
The write cycle time is the time from a valid stop condition of a write sequence to the end of the internal erase/write cycle. During the write cycle, the X24645 bus interface circuits are disabled, SDA is allowed to remain HIGH, and the device does not respond to its slave address.

Bus Timing

Guidelines for Calculating Typical Values of Bus Pull-Up Resistors

$$R_{Min.} = \frac{V_{CC\,Max.}}{I_{OL\,Min.}} = 1.8K\Omega$$

$$R_{MAX.} = \frac{t_R}{C_{BUS}}$$

Max. Resistance

Min. Resistance

Resistance (KΩ) — vertical axis: 0, 20, 40, 60, 80, 100, 120

Bus Capacitance (pF) — horizontal axis: 0, 20, 40, 60, 80, 100, 120

SYMBOL TABLE

WAVEFORM	INPUTS	OUTPUTS
	Must be steady	Will be steady
	May change from Low to High	Will change from Low to High
	May change from High to Low	Will change from High to Low
	Don't Care: Changes Allowed	Changing: State Not Known
	N/A	Center Line is High Impedance

PACKAGING INFORMATION

8-Lead Plastic Small Outline Gull Wing Package Type S

Pin 1 Index

Pin 1

0.150 (3.80) / 0.158 (4.00)

0.228 (5.80) / 0.244 (6.20)

0.014 (0.35) / 0.019 (0.49)

0.188 (4.78) / 0.197 (5.00)

(4X) 7°

0.053 (1.35) / 0.069 (1.75)

0.050 (1.27)

0.004 (0.19) / 0.010 (0.25)

0.010 (0.25) / 0.020 (0.50) X 45°

0° - 8°

0.0075 (0.19) / 0.010 (0.25)

0.016 (0.410) / 0.037 (0.937)

0.050" Typical

0.050" Typical

0.250"

0.030" Typical 8 Places

FOOTPRINT
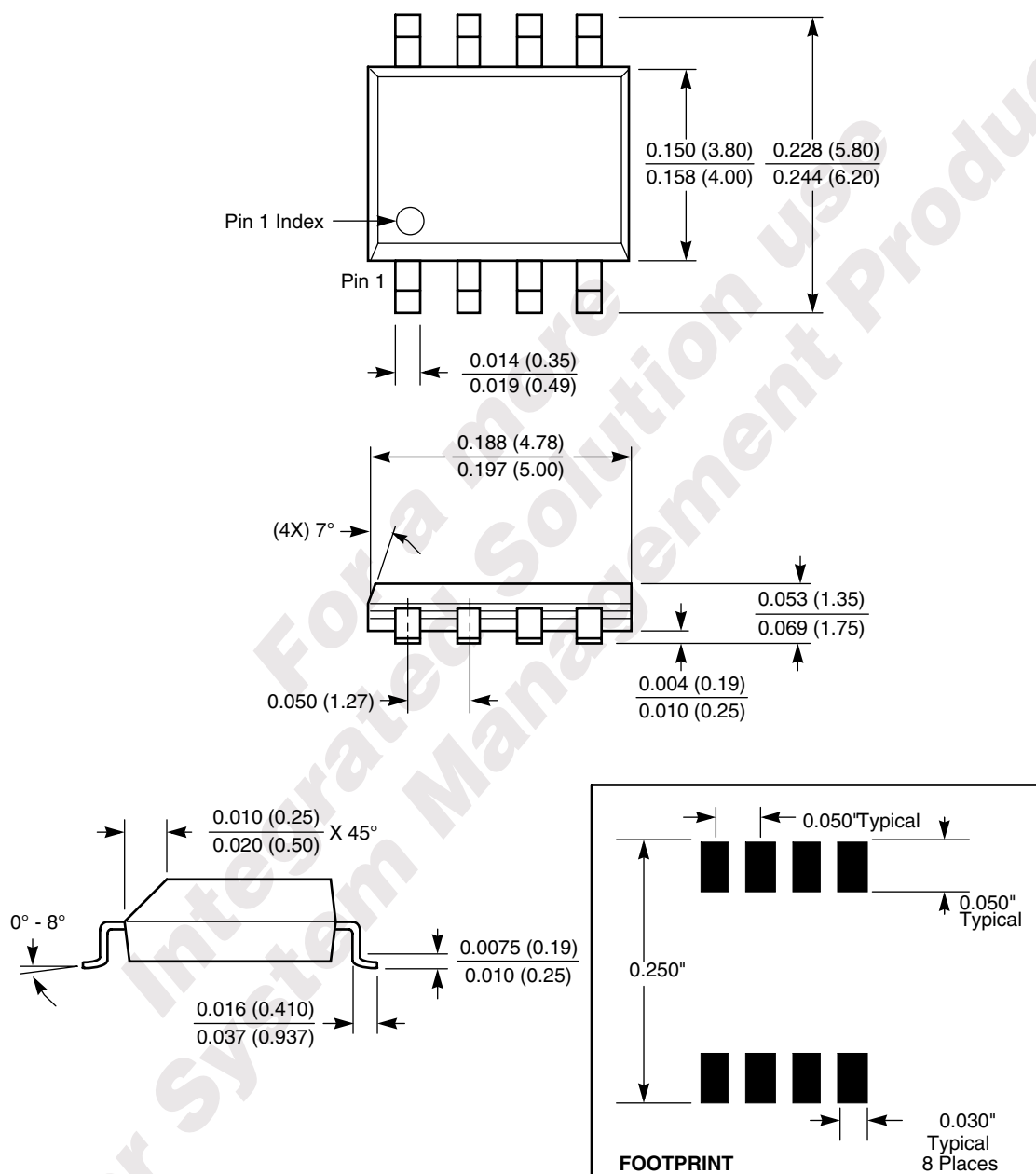
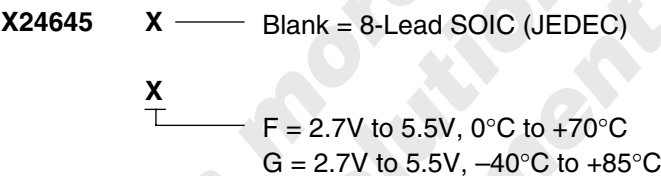**NOTE: ALL DIMENSIONS IN INCHES (IN PARENTHESES IN MILLIMETERS)**

X24645 – Preliminary Information

Ordering Information

X24645   X   X   -X

Device ─────────┘

V$_{CC}$ Range
2.7 = 2.7V to 5.5V

Temperature Range
Blank = 0°C to +70°C
I = −40°C to +85°C

Package
S8 = 8-Lead SOIC (JEDEC)

Part Mark Convention

X24645   X ─── Blank = 8-Lead SOIC (JEDEC)

X
└─ F = 2.7V to 5.5V, 0°C to +70°C
G = 2.7V to 5.5V, −40°C to +85°C

Product Change Notice : PCN February 4, 2000

February 4, 2000
Ref: PCN-00-01

Dear Xicor Customer,

At Xicor, we continuously strive to improve the performance and efficiency of our operations, and the quality of our products. Consistent with this effort, we are currently adding additional wafer fabrication capacity for various IIC and SPI serial products.

This added wafer fabrication capacity will complement current operations and will expand Xicor's capabilities to accommodate future growth.

In addition, several of the IIC and SPI serial products are undergoing a die revision change. The new die revision is functionally and pin to pin compatable with the existing die revision.

See the detailed product number list below for the implementation date and description of the change. Samples for qualification will be available approximately 4 weeks before the implementation date. Qualification data is available upon request.

If you have any further questions, please contact your regional Xicor sales office.

Sincerely,

Xicor Marketing Department

Xicor Part Number	Implement Date	Description of Change
IIC Serial Products		
X24164P	2/28/00	Foundry Change
X24164P-3	2/28/00	Foundry Change
X24164PI	2/28/00	Foundry Change
X24164PI-3	2/28/00	Foundry Change
X24164S	2/28/00	Foundry Change
X24164S-2.7	2/28/00	Foundry Change
X24164S-3	2/28/00	Foundry Change
X24164SI	2/28/00	Foundry Change
X24164SI-2.7	2/28/00	Foundry Change
X24C04P	5/31/00	Die Rev / Foundry Change
X24C04P-2.7	5/31/00	Die Rev / Foundry Change
X24C04P-3	5/31/00	Die Rev / Foundry Change
X24C04P-3.5	5/31/00	Die Rev / Foundry Change
X24C04PI	5/31/00	Die Rev / Foundry Change
X24C04PI-2.7	5/31/00	Die Rev / Foundry Change

X24C04PI-3	5/31/00	Die Rev / Foundry Change
X24C04PI-3.5	5/31/00	Die Rev / Foundry Change
X24C04PM	5/31/00	Die Rev / Foundry Change
X24C04PM-3	5/31/00	Die Rev / Foundry Change
X24C04PM-3.5	5/31/00	Die Rev / Foundry Change
X24C04S14	5/31/00	Die Rev / Foundry Change
X24C04S14-3	5/31/00	Die Rev / Foundry Change
X24C04S14-3.5	5/31/00	Die Rev / Foundry Change
X24C04S14I	5/31/00	Die Rev / Foundry Change
X24C04S14I-3	5/31/00	Die Rev / Foundry Change
X24C04S14I-3.5	5/31/00	Die Rev / Foundry Change
X24C04S14M	5/31/00	Die Rev / Foundry Change
X24C04S14M-3	5/31/00	Die Rev / Foundry Change
X24C04S14M-3.5	5/31/00	Die Rev / Foundry Change
X24C04S8	5/31/00	Die Rev / Foundry Change
X24C04S8-2.7	5/31/00	Die Rev / Foundry Change
X24C04S8-3	5/31/00	Die Rev / Foundry Change
X24C04S8-3.5	5/31/00	Die Rev / Foundry Change
X24C04S8I	5/31/00	Die Rev / Foundry Change
X24C04S8I-2.7	5/31/00	Die Rev / Foundry Change
X24C04S8I-3	5/31/00	Die Rev / Foundry Change
X24C04S8I-3.5	5/31/00	Die Rev / Foundry Change
X24C04S8M	5/31/00	Die Rev / Foundry Change
X24C04S8M-3	5/31/00	Die Rev / Foundry Change
X24C04S8M-3.5	5/31/00	Die Rev / Foundry Change
X24C08P	8/31/00	Die Rev / Foundry Change
X24C08P-2.7	8/31/00	Die Rev / Foundry Change
X24C08P-3	8/31/00	Die Rev / Foundry Change
X24C08P-3.5	8/31/00	Die Rev / Foundry Change
X24C08PI	8/31/00	Die Rev / Foundry Change
X24C08PI-2.7	8/31/00	Die Rev / Foundry Change
X24C08PI-3	8/31/00	Die Rev / Foundry Change
X24C08PI-3.5	8/31/00	Die Rev / Foundry Change
X24C08PM	8/31/00	Die Rev / Foundry Change
X24C08PM-3	8/31/00	Die Rev / Foundry Change
X24C08PM-3.5	8/31/00	Die Rev / Foundry Change
X24C08S	8/31/00	Die Rev / Foundry Change
X24C08S-3	8/31/00	Die Rev / Foundry Change
X24C08S-3.5	8/31/00	Die Rev / Foundry Change
X24C08S8	8/31/00	Die Rev / Foundry Change
X24C08S8-2.7	8/31/00	Die Rev / Foundry Change
X24C08S8-3	8/31/00	Die Rev / Foundry Change
X24C08S8I	8/31/00	Die Rev / Foundry Change
X24C08S8I-2.7	8/31/00	Die Rev / Foundry Change

X24C08S8I-3	8/31/00	Die Rev / Foundry Change
X24C08S8M	8/31/00	Die Rev / Foundry Change
X24C08SI	8/31/00	Die Rev / Foundry Change
X24C08SI-3	8/31/00	Die Rev / Foundry Change
X24C08SI-3.5	8/31/00	Die Rev / Foundry Change
X24C08SM	8/31/00	Die Rev / Foundry Change
X24C08SM-3	8/31/00	Die Rev / Foundry Change
X24C08SM-3.5	8/31/00	Die Rev / Foundry Change
SPI Serial Products		
X25020P	7/31/00	Die Rev / Foundry Change
X25020P-2.7	7/31/00	Die Rev / Foundry Change
X25020PI	7/31/00	Die Rev / Foundry Change
X25020PI-2.7	7/31/00	Die Rev / Foundry Change
X25020S	7/31/00	Die Rev / Foundry Change
X25020S-2.7	7/31/00	Die Rev / Foundry Change
X25020S-3	7/31/00	Die Rev / Foundry Change
X25020SI	7/31/00	Die Rev / Foundry Change
X25020SI-2.7	7/31/00	Die Rev / Foundry Change
X25020SI-3	7/31/00	Die Rev / Foundry Change
X25040P	7/31/00	Die Rev / Foundry Change
X25040P-2.7	7/31/00	Die Rev / Foundry Change
X25040PI	7/31/00	Die Rev / Foundry Change
X25040PI-2.7	7/31/00	Die Rev / Foundry Change
X25040S	7/31/00	Die Rev / Foundry Change
X25040S-2.7	7/31/00	Die Rev / Foundry Change
X25040SI	7/31/00	Die Rev / Foundry Change
X25040SI-2.7	7/31/00	Die Rev / Foundry Change
X25040SM	7/31/00	Die Rev / Foundry Change
X25160S	8/31/00	Foundry Change
X25160S-2.7	8/31/00	Foundry Change
X25160SI	8/31/00	Foundry Change
X25160SI-2.7	8/31/00	Foundry Change
X25320P	8/31/00	Foundry Change
X25320S	8/31/00	Foundry Change
X25320S-2.7	8/31/00	Foundry Change
X25320SI	8/31/00	Foundry Change
X25320SI-2.7	8/31/00	Foundry Change

February 4, 2000

Dear Xicor Customer,

At Xicor, we continuously strive to improve the performance and efficiency of our operations, and the quality of our products. Consistent with this effort, we are revising the tape and reel "T" codes to eliminate partial reel quantities.

See the detailed tape and reel "T" codes definitions list and definitions matrix below . The implementation date for the new tape and reel "T" codes is March 1, 2000. All existing orders with shipment dates on or after March 1, 2000 will be converted to the new tape and reel "T" codes. All new orders on or after March 1, 2000 must use the new tape and reel "T" codes.

If you have any further questions, please contact your regional Xicor sales office.

Sincerely,

Xicor Marketing Department

Tape and Reel "T" Code Definitions

CODE	PACKAGE	QTY	REQUIREMENTS	REEL SIZE
T1	SOIC (150 MIL SOIC) "S"	=2500	Tape and Reel	13"
T1	SOIC (300 MIL SOIC) "S"	=1000	Tape and Reel	13"
T1	EIAJ (WIDE SOIC) "A"	=2000	Tape and Reel	13"
T1	TSOP (THIN SOIC) "T"	=1000	Tape and Reel	13"
T1	PLCC "J"	=750	Tape and Reel	13"
T1	MSOP "M"	=2500	Tape and Reel	13"
T1	GULL WING "R"	=500	Tape and Reel	13"
T1	TSSOP "V"	=2500	Tape and Reel	13"
T1	XBGA "B" or "Z"	=10000	Tape and Reel	13"
T2	SOIC (150 MIL SOIC) "S"	=1000	Tape and Reel	7"
T2	SOIC (300 MIL SOIC) "S"	=500	Tape and Reel	13"
T2	EIAJ (WIDE SOIC) "A"	=1000	Tape and Reel	7"

T2	TSOP (THIN SOIC) "T"	=500	Tape and Reel	13"
T2	PLCC "J"	=500	Tape and Reel	13"
T2	MSOP "M"	=1000	Tape and Reel	7"
T2	GULL WING "R"	=250	Tape and Reel	13"
T2	TSSOP "V"	=1000	Tape and Reel	7"
T2	XBGA "B" or "Z"	=5000	Tape and Reel	13"
T3	SOIC (150 MIL SOIC) "S"	=2500	Tape and Reel & Dry Pack	13"
T3	SOIC (300 MIL SOIC) "S"	=1000	Tape and Reel & Dry Pack	13"
T3	EIAJ (WIDE SOIC) "A"	=2000	Tape and Reel & Dry Pack	13"
T3	TSOP (THIN SOIC) "T"	=1000	Tape and Reel & Dry Pack	13"
T3	PLCC "J"	=750	Tape and Reel & Dry Pack	13"
T3	MSOP "M"	=2500	Tape and Reel & Dry Pack	13"
T3	GULL WING "R"	=500	Tape and Reel & Dry Pack	13"
T3	TSSOP "V"	=2500	Tape and Reel & Dry Pack	13"
T3	XBGA "B" or "Z"	=10000	Tape and Reel & Dry Pack	13"
T4	SOIC (150 MIL SOIC) "S"	=1000	Tape and Reel & Dry Pack	7"
T4	SOIC (300 MIL SOIC) "S"	=500	Tape and Reel & Dry Pack	13"
T4	EIAJ (WIDE SOIC) "A"	=1000	Tape and Reel & Dry Pack	7"
T4	TSOP (THIN SOIC) "T"	=500	Tape and Reel & Dry Pack	13"
T4	PLCC "J"	=500	Tape and Reel & Dry Pack	13"
T4	MSOP "M"	=1000	Tape and Reel & Dry Pack	7"
T4	GULL WING "R"	=250	Tape and Reel & Dry Pack	13"
T4	TSSOP "V"	=1000	Tape and Reel & Dry Pack	7"
T4	XBGA "B" or "Z"	=5000	Tape and Reel & Dry Pack	13"
T5	MSOP "M"	=3500	Tape and Reel	13"
T5	TSSOP "V"	=3500	Tape and Reel	13"
T5	XBGA "B" or "Z"	=2500	Tape and Reel	13"
T6	MSOP "M"	=3500	Tape and Reel & Dry Pack	13"
T6	TSSOP "V"	=3500	Tape and Reel & Dry Pack	13"
T6	XBGA "B" or "Z"	=2500	Tape and Reel & Dry Pack	13"

T6	XBGA "B" or "Z"	=2500	Tape and Reel & Dry Pack	13"
T7	ALL PACKAGES	ALL QTYS.	Dry Pack	N/A

Tape and Reel "T" Code Definition Matrix

150 MIL SOIC "S" (8L, 14L,16L)			
Code	2500	1000	Dry Pack
T1	x	x	x
T2	x	x	x
T3	x		x
T4	x	x	x
T7*	x	x	x

*NOTE: DRY PACK ONLY

TSOP THIN SOIC "T"			
Code	1000	500	Dry Pack
T1	x	x	x
T2	x	x	x
T3	x	x	x
T4	x	x	x
T7*	x	x	x

*NOTE: DRY PACK ONLY

GULL WING "R"			
Code	500	250	Dry Pack
T1	x	x	x
T2	x	x	x
T3	x	x	X
T4	x	x	X
T7*	x	x	x

*NOTE: DRY PACK ONLY

300 MIL SOIC "S" (20L, 24L, 28L)

Code	1000	500	Dry Pack
T1	X	x	x
T2	x	X	x
T3	X	x	X
T4	x	X	X
T7*	x	x	X

*NOTE: DRY PACK ONLY

XBGA "B" or "Z"

Code	10000	5000	2500	Dry Pack
T1	x	x	x	x
T2	x	x	x	x
T3	x	x	x	x
T4	x	x	x	x
T5	x	x	x	x
T6	x	x	x	x
T7*	x	x	x	x

*NOTE: DRY PACK ONLY

EIAJ "A"

Code	2000	1000	Dry Pack
T1	x	x	x
T2	x	x	x
T3	x	x	x
T4	x	x	x
T7*	x	x	x

*NOTE: DRY PACK ONLY

PLCC "J"

Code	750	500	Dry Pack
T1	x	x	x
T2	x	x	x
T3	x	x	X
T4	x	x	X
T7*	x	x	X

*NOTE: DRY PACK ONLY

TSSOP "V"

Code	2500	1000	3500	Dry Pack
T1	x	x	x	x
T2	x	x	x	x
T3	x	x	x	x
T4	x	x	x	x
T5	x	x	x	x
T6	x	x	x	x
T7*	x	x	x	x

*NOTE: DRY PACK ONLY

MSOP "M"

Code	2500	1000	3500	Dry Pack
T1	x	x	x	x
T2	x	x	x	x
T3	x	x	x	x
T4	x	x	x	x
T5	x	x	x	x
T6	x	x	x	x

T7*	x	x	x	x

*NOTE: DRY PACK ONLY
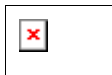
Our web site makes extensive use Adobe Acrobat (PDF) documents to provide you with the highest quality in electronic publishing. If you do not have the Adobe Acrobat Reader, click this hyperlink for a free copy.

Home | Products | Corporate | Support | Reps & Disti's | What's New
Cool Jobs | Contact Info | Datasheets | Search | Site Map
Copyright © 2000 Xicor Inc.